Title (en)
HONEYCOMB-BASED HIGH TEMPERATURE STRUCTURAL DAMPER

Title (de)
WABENBASIERTER HOCHTEMPERATUR-STRUKTURDÄMPFER

Title (fr)
AMORTISSEUR STRUCTUREL HAUTE TEMPÉRATURE À BASE DE NID D'ABEILLES

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Abstract (en)
[origin: EP2674091A1] The present invention is concerned with a honeycomb based high temperature structural damper laminate, based on a core structure comprising a honeycomb laminated with a layer of a structural damping material. The present invention also provides a method for producing said laminate as well as the use of said laminate in various fields of application.

IPC 8 full level
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US 2004219322 A1 20041104 - FISHER DENNIS K [US], et al

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